



S1MSP1M

# 1.0A SURFACE MOUNT STANDARD RECOVERY RECTIFIER PowerDI123

#### Product Summary (@T<sub>A</sub> = +25°C)

V <sub>RRM</sub> (V)	I <sub>O</sub> (A)	V <sub>F</sub> Max (V)	I <sub>R</sub> Max (μA)
1,000	1.0	1.1	10

### **Description and Applications**

The DIODES™ S1MSP1M is a rectifier packaged in the PowerDI<sup>®</sup>123 package. Providing high-reverse breakdown voltage and high-current capability for standard rectification, this device is ideal for use in applications such as:

- Switching-mode power-supply applications
- DC-DC converter applications
- · AC-DC adaptors/chargers
- Mobile devices
- LED lighting

#### **Features and Benefits**

- Glass Passivated Die Construction
- Ideally Suited for Automated Assembly
- Low Profile Design, Package Height Less than 1.0mm
- Low Reverse Leakage Current
- Exceptional Thermal Transfer Based on Exposed Heat Sink on the Underside of the Device
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/104/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative.

https://www.diodes.com/quality/product-definitions/

#### **Mechanical Data**

- Package: PowerDI123
- Package Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208 <sup>3</sup>
- Polarity: Cathode Band
- Weight: 0.01 grams (Approximate)

#### PowerDI123



Top View

### **Ordering Information** (Note 4)

Part Number	Backago	Packing		
Fait Number	Package	Qty.	Carrier	
S1MSP1M-7	PowerDI123	3,000	Tape & Reel	

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

## Marking Information



PowerDI123

G20 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: J = 2022) M = Month (ex: 9 = September)

Date Code Key

Year	2022	2023	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033
Code	J	K	L	М	N	0	Р	R	S	Т	U	V
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec

PowerDI is a registered trademark of Diodes Incorporated.



### **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit	
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V <sub>RRM</sub> V <sub>RWM</sub> V <sub>RM</sub>	1,000	٧
RMS Reverse Voltage		V <sub>R(RMS)</sub>	700	V
Average Rectified Output Current	@ T <sub>A</sub> = +30°C	lo	1.0	A
Non-Repetitive Peak Forward Surge Currer 8.3ms Single Half Sine-Wave Superimpose	I <sub>FSM</sub>	25	А	

### **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Case (Note 5)	R <sub>0JC</sub>	25	°C/W
Typical Thermal Resistance Junction to Ambient (Note 5)	$R_{\theta JA}$	137	°C/W
Typical Thermal Resistance, Junction to Lead (Note 5)	R <sub>0JL</sub>	20	°C/W
Typical Thermal Resistance, Junction to Case (Note 6)	Rejc	6	°C/W
Typical Thermal Resistance Junction to Ambient (Note 6)	$R_{\theta JA}$	54	°C/W
Typical Thermal Resistance, Junction to Lead (Note 6)	$R_{ heta JL}$	5	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

### Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V <sub>(BR)R</sub>	1,000	_	_	V	$I_R = 5\mu A$
Forward Voltage Drop	V <sub>F</sub>	_	0.98	1.1	V	I <sub>F</sub> = 1A, T <sub>J</sub> = +25°C
Leakage Current (Note 7)	1-	_	0.5	10	μA	V <sub>R</sub> = 1,000V, T <sub>J</sub> = +25°C
Leakage Current (Note 1)	I <sub>R</sub>	_	12	100	μΑ	$V_R = 1,000V, T_J = +125$ °C
Reverse Recovery Time	t <sub>rr</sub>	_	1.2	_	μs	$I_F = 0.5A$ , $I_R = 1.0A$ , $I_{RR} = 0.25A$
Total Capacitance	C <sub>T</sub>	_	2.8	_	pF	$V_R = 4.0V_{DC}$ , $f = 1MHz$

Notes:

- 5. Device mounted on FR-4 substrate PC board, with minimum recommended pad layout.
- Device mounted on 1" x 1", FR-4 PCB; 2oz. Cu pad layout as shown on Diodes Incorporated's website at http://www.diodes.com/package-outlines.html. T<sub>A</sub> = +25°C.
   Short duration test pulse used to minimize self-heating effect.



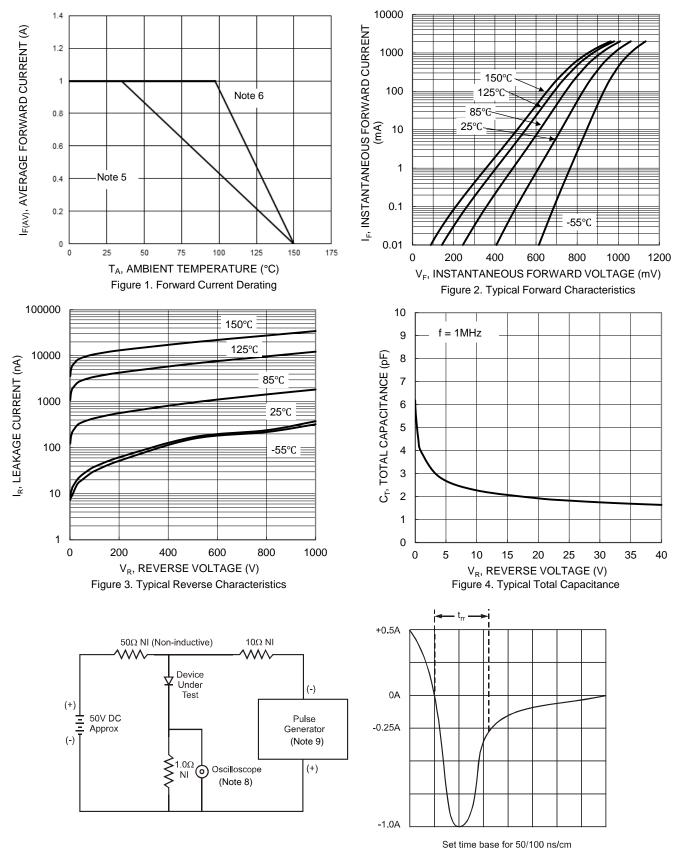


Figure 5. Reverse Recovery Time Characteristic and Test Circuit

Notes: 8. Rise time = 7.0ns max. Input impedance =  $1.0M\Omega$ , 22pF.

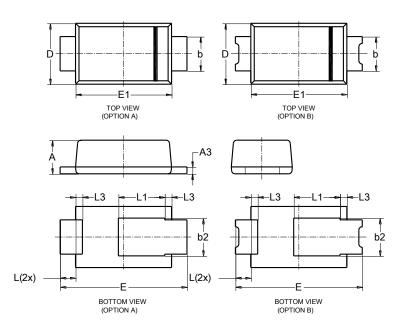
9. Rise time = 10ns max. Input impedance =  $50\Omega$ .



### **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI123

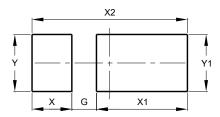


PowerDI123						
Dim	Min	Max	Тур			
Α	0.93	1.00	0.98			
A3	0.15	0.25	0.20			
b	0.85	1.25	1.00			
b2	1.025	1.125	1.10			
D	1.63	1.93	1.78			
Е	3.50	3.90	3.70			
E1	2.60	3.00	2.80			
L	0.40	0.50	0.45			
L1	1.25	1.40	1.35			
L3	0.125	0.275	0.20			
All Dimensions in mm						

# Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI123



Dimensions	Value (in mm)		
Dillielisions			
G	0.65		
Х	1.05		
X1	2.40		
X2	4.10		
Y	1.50		
Y1	1.50		



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